

# 2.4GHz Loop Chip Antenna



AANI-CH-0070

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1.0 x 0.5 x 0.4 mm  
RoHS/RoHS II Compliant  
MSL Level = 1

## Reflow Profile [JEDEC J-STD-020]

Solder paste: Sn/3.0Ag/0.5Cu

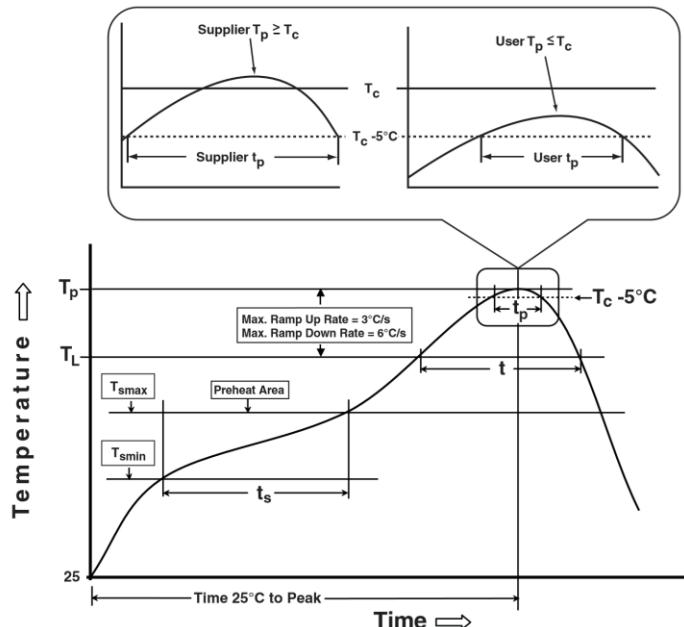


Table 1

### SnPb Eutectic Process Classification Temperatures ( $T_c$ )

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> ≥350
<2.5mm	235°C	220°C
≥2.5mm	220°C	220°C

Table 2

### Pb-Free Process Classification Temperatures ( $T_c$ )

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350-2000	Volume mm <sup>3</sup> >2000
<1.6mm	260°C	260°C	260°C
1.6mm - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat / soak		
Temperature minimum ( $T_{smin}$ )	100°C	150°C
Temperature maximum ( $T_{smax}$ )	150°C	200°C
Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60 – 120 sec.	60 – 90 sec.
Average ramp-up rate ( $T_{smax}$ to $T_p$ )	3°C/sec. max	3°C/sec. max
Liquidous temperature ( $T_L$ )	183°C	217°C
Time at Liquidous ( $T_L$ )	60 – 150 sec.	60 – 150 sec.
Peak package body temperature ( $T_p$ )*	See Table 1	See Table 2
Time ( $T_p$ )** within 5°C of the specified classification temperature ( $T_c$ )	20 sec.	10 sec.
Ramp-down rate ( $T_p$ to $T_{smax}$ )	6°C/sec. max	6°C/sec. max
Time 25°C to peak temperature	6 min. max	8 min. max
Reflow cycles	2 max	2 max

\*Tolerance for peak profile temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum.

\*\*Tolerance for time at peak profile temperature ( $t_p$ ) is defined as a supplier minimum and a user maximum.